

Small Signal Schottky Diode

Features

- Fast Switching Speed
- Protected by a PN junction guard ring against excessive
- Low Turn-on Voltage
- For General Purpose Application

Mechanical Data

- Case: Minimelf, Glass
- Terminals: Solderable per MIL-STD-202, Method 208
- Polarity: Indicated by Cathode Band
- Weight: 0.05 grams (approx.)

Maximum Ratings @ 25°C Unless Otherwise Specified

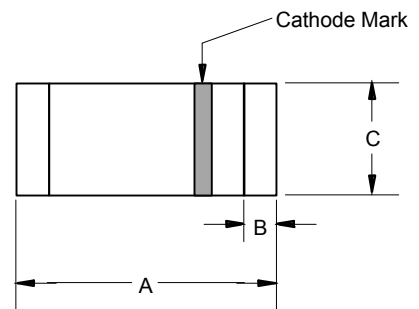
Characteristic	Symbol	Value	Unit
Peak Reverse Voltage	V_{RRM}	40	V
Forward Continuous Current(Note1)	I_F	350	mA
Surge Forward Current @ $t_p < 10ms$, $T_A=25^\circ C$	I_{FSM}	7.5	A
Power Dissipation(Note 1)	P_{tot}	330	mW
Thermal Resistance(Note 1)	$R_{\theta JA}$	300	K/W
Operation Temperature Range	T_A	-55 to 125	°C
Storage Temperature Range	T_{STG}	-55 to 150	°C

Electrical Characteristics @ 25°C Unless Otherwise Specified

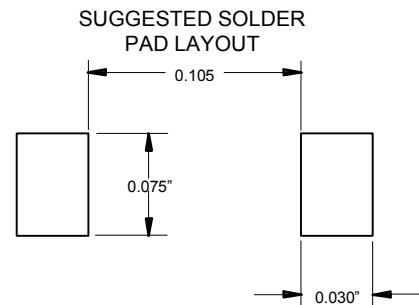
Charateristic	Symbol	Min	Typ.	Max	Unit	Test Cond.
Reverse Breakdown Volt.	$V_{(BR)R}$	40	-----	-----	V	100uA pulse
Reverse Leakge Current.	I_R	-----	-----	2 15 5 25 25 50	uA	$V_R=10V$ $V_R=10V, T_J=60^\circ C$ $V_R=20V$ $V_R=20V, T_J=60^\circ C$ $V_R=40V$ $V_R=40V, T_J=60^\circ C$
Forward Volt. Drop	V_F	-----	-----	0.25 0.45 0.90	V	$I_F=0.1mA$ $I_F=10mA$ $I_F=250mA$
Junction Capacitance	C_{tot}	-----	2.0	-----	pF	$V_R=1V, f=1MHz$

Note: 1. Valid provided that electrodes are kept at ambient temperature

MINIMELF



DIM	DIMENSION				NOTE
	INCHES		MM		
	MIN	MAX	MIN	MAX	
A	.134	.142	3.40	3.60	
B	.008	.016	0.20	0.40	
C	.055	.059	1.40	1.50	



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Figure 1. Forward current versus forward voltage at different temperatures (typical values)

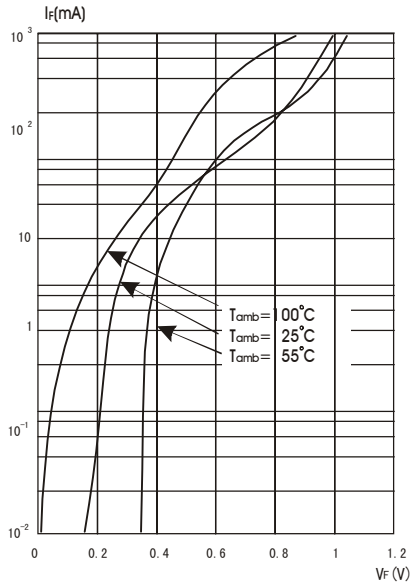


Figure 2. Forward current versus forward voltage (typical values)

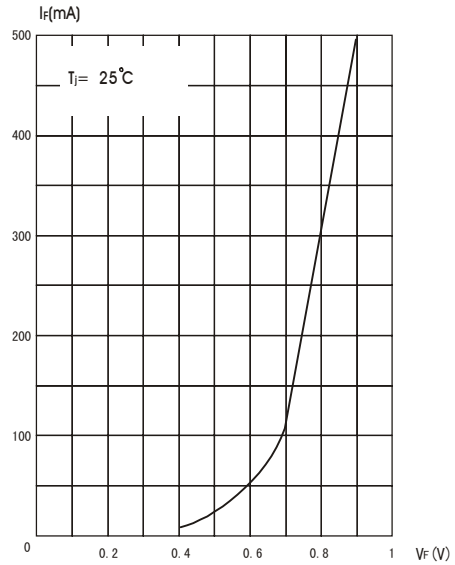
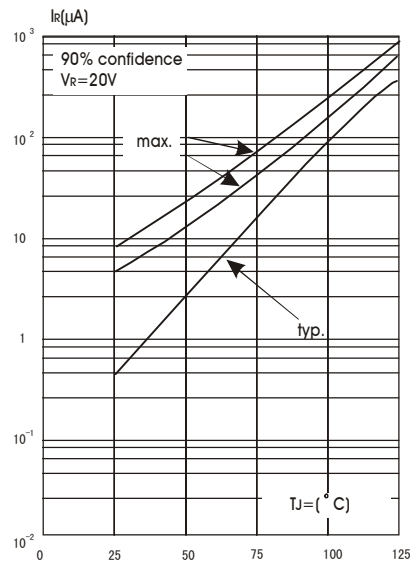


Figure 3. Reverse current versus ambient temperatures



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Figure 4. Reverse current versus continuous Reverse voltage (typical values)

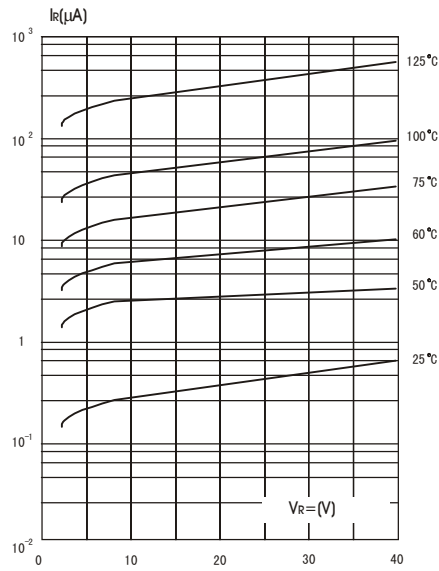


Figure 5. Capacitance C versus reverse applied voltage V_R (typical values)

